



APPLICATION DATA SHEET

Electronic Version v14

Stylesheet Version v14.0

Title of Invention	WAFER ACCEPTANCE TESTING METHOD AND STRUCTURE OF A TEST KEY USED IN THE METHOD		
Application Type : regular, utility Attorney Docket Number : NTCP0026USA			
Correspondence address: Customer Number: 027765 			
Inventor Information: <u>Inventor 1:</u> Applicant Authority Type: Inventor Citizenship: TW Given Name: Ping Family Name: Hsu Residence: City of Residence: Taipei Hsien Country of Residence: TW Address-1 of Mailing Address: No. 4, Lane 106, Chung-Hsiao St., Chung-Ho City Address-2 of Mailing Address: City of Mailing Address: Taipei Hsien State of Mailing Address: Postal Code of Mailing Address: Country of Mailing Address: TW Phone: Fax: E-mail:			
Attorney Information: practitioner(s) at Customer Number: 027765  as my attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.			